

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon Carbide (SiC)	409-21-2	0	0.0	0
			Subtotal	0	0	0
Wire	Pure metal	Aluminium (Al)	7429-90-5	0	100.0	0
			Subtotal	0	100	0
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0	5.0	0.12
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.06
	Lead alloy	Lead (Pb)	7439-92-1	0.04	92.5	2.17
			Subtotal	0.04	100	2.35
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.37	100.0	22
			Subtotal	0.37	100	22
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.2
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	67.22	99.87	3984.81
			Subtotal	67.31	100	3990
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.1	6.5	124.34
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.16	16.0	306.08
	Filler	Silica fused	60676-86-0	22.91	71.0	1358.23
	Flame retardant	Metal hydroxide		2.1	6.5	124.34
			Subtotal	32.27	100	1912.99
			Total	99.99	100	5927.34

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